

Abstract

A soldering flux suitable for soldering of small electronic components comprises 0.1 - 50 mass percent of an organic acid, 5 - 40 mass percent of a solvent, and 10 - 95 mass percent of a thermosetting resin (including a curing agent), which is preferably a bisphenol A epoxy resin and an acid anhydride or amine curing agent. This flux can be used to prepare a solder paste by mixing with solder powder. This soldering flux can secure an electronic component simultaneously by soldering and by the resin, simply by a soldering operation at a soldering temperature of at least 150°C, and cleaning after soldering is no longer necessary.